imall

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

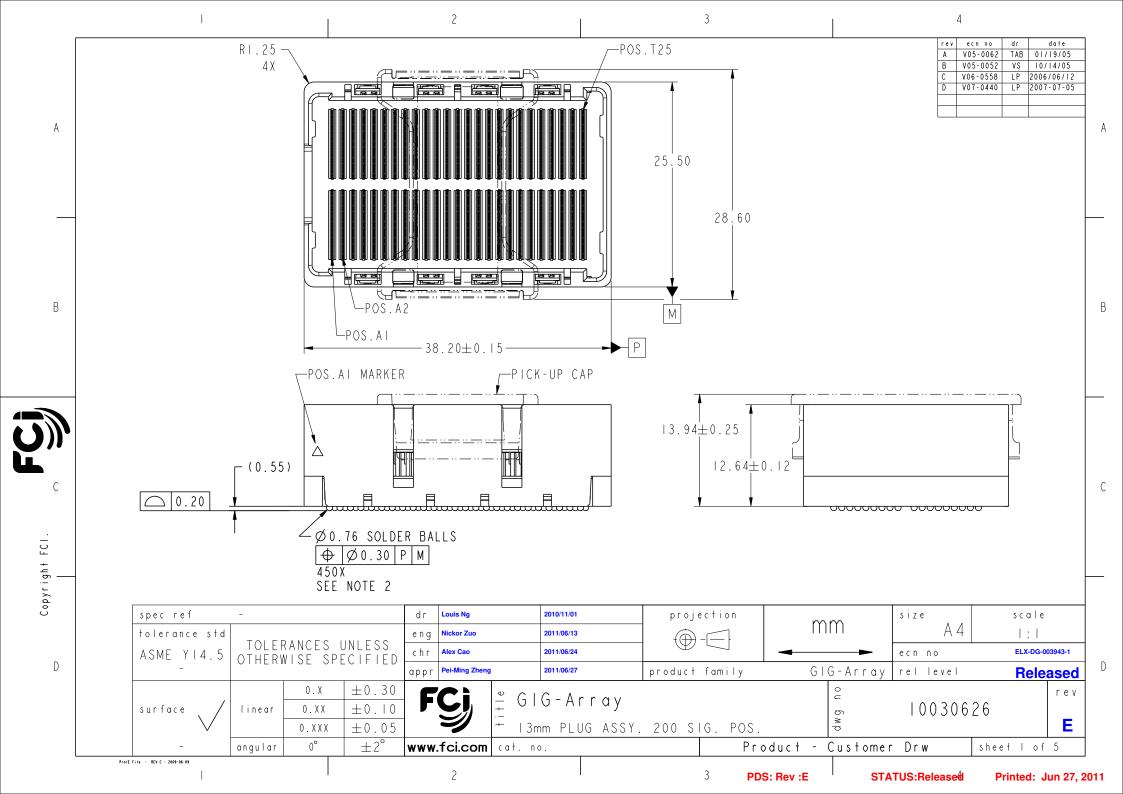
We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!

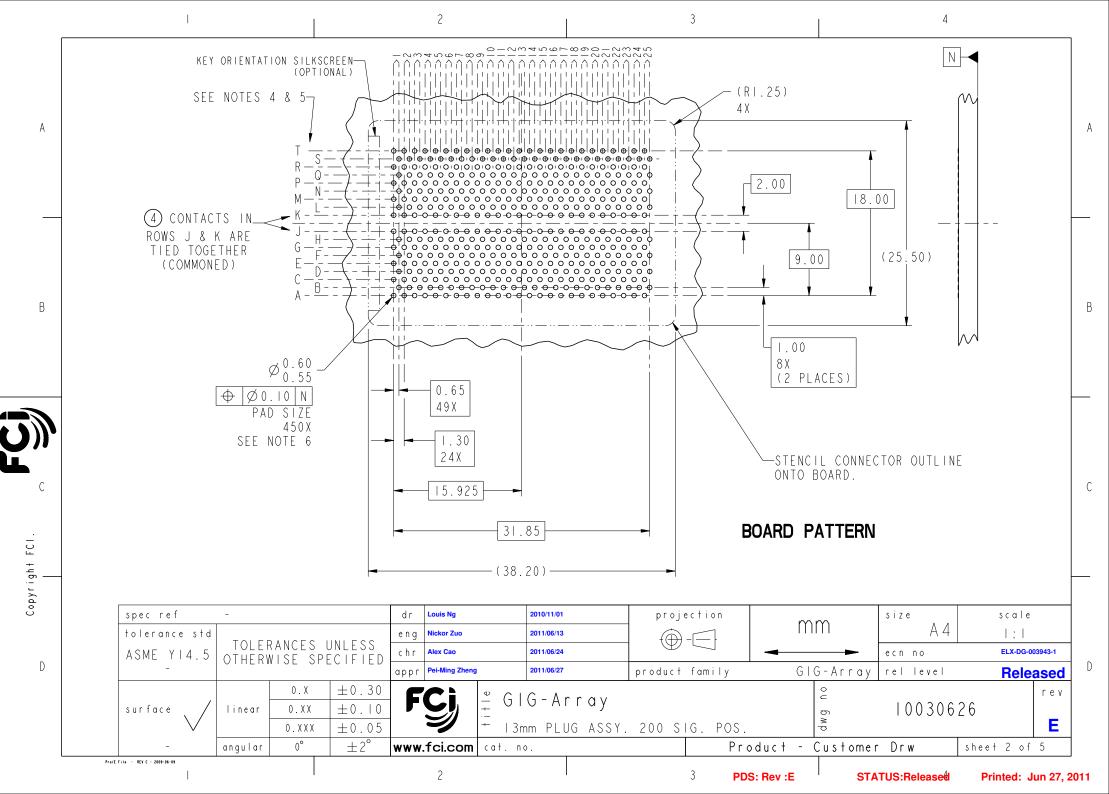


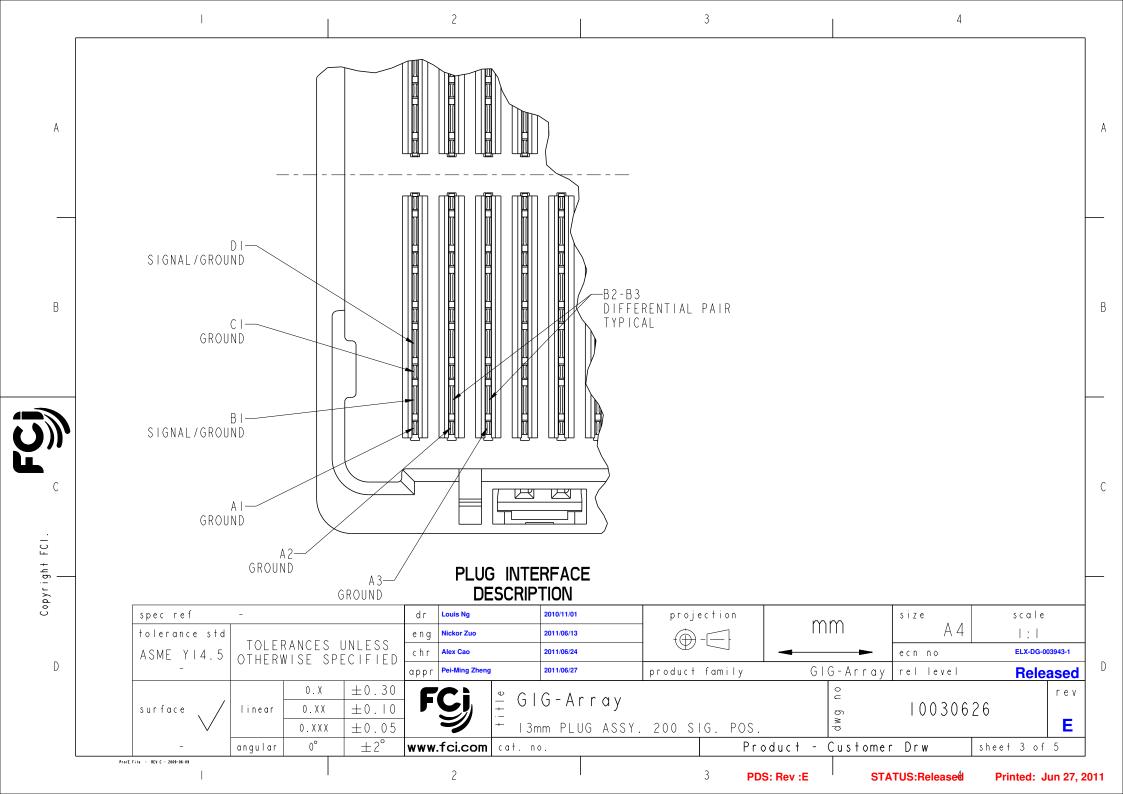
Contact us

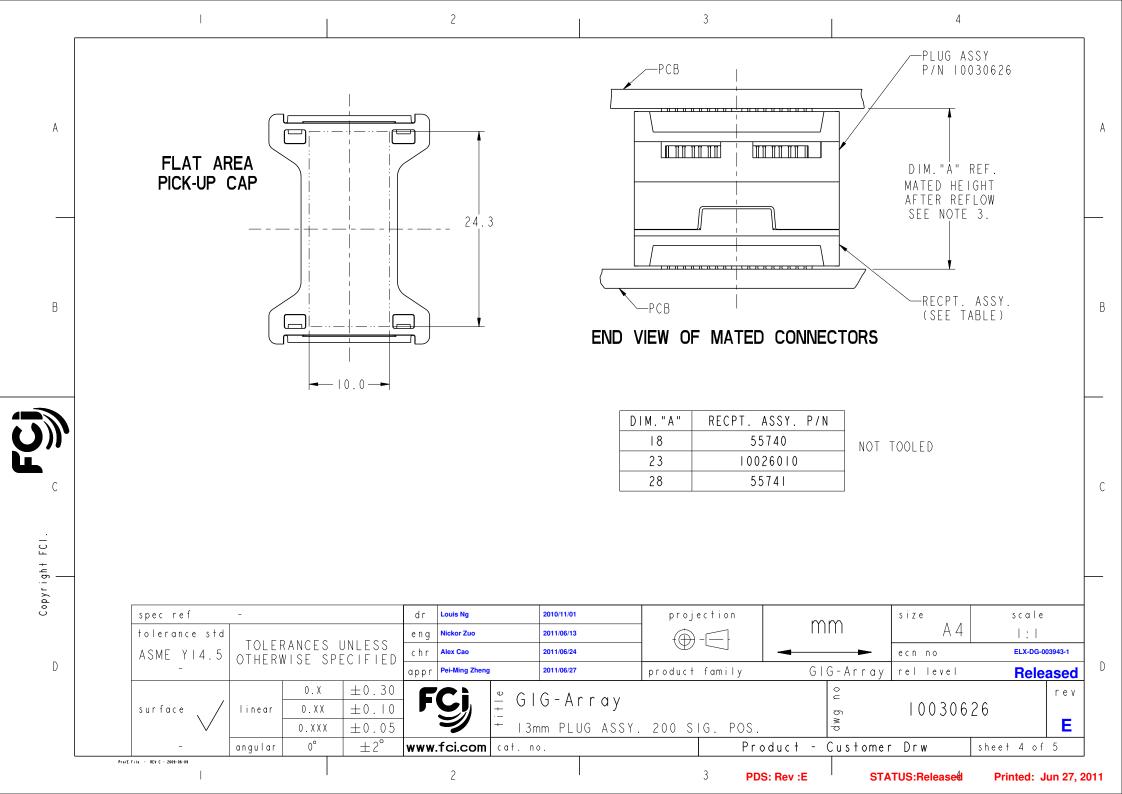
Tel: +86-755-8981 8866 Fax: +86-755-8427 6832 Email & Skype: info@chipsmall.com Web: www.chipsmall.com Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China











	PRODUCT NUMBER	SOLDER BAL	L COMPOS	SITION		CT PLATING PERFORM			·		
	10030626-001	STANDARD	(EUTEC	- IC)		-BASED PLATING, QU					
	10030626-001LF	DILF LEADFREE			GS-12-192,1	MENTS OF FCI PRODU NCLUDING TELCORDI	CENTRAL OFFICE				
A	10030626-201	201 STANDARD (EUTECTIC)		- IC)	Au avas Ni						
	I0030626-20ILF LEADFREE					Au over Ni					
			NOTES	• •							
			() м	ATERIAL :			NOTES CONTINUED				
_			Ŭ	HOUSING:	LCP Copper Alloy		0	ITIONAL TOLERANCE DEFI			
				PLATING	(CONTACT): Au (VER Ni.	OF LAND PATTER	N LAND PATTERN. POSIT N TO FUDICIAL MARKS OF	R PCB DATUMS		
				SOLDER B	IG: 94 V-O ALL: (SEE TABLE) EUTECTIC	PRODUCT APPLIC	ED BY CUSTOMER. FOR F ATION AND PCB DESIGN E			
				SnPb OR	LEADFREE 95.5 S	on/4Ag/0.5Cu	DOC. NO. GS-20 DOC. PROPER APPI	-016. _ICATION FOLLOW FCI AF	PPIICATION		
В			\sim		LS WILL NOT BE		SPECIFICATION G	S-20-033 LEADFREE SOLD PROPERLY IN A LEADED	DER BALLS		
			SH -	PERICAL S	HAPE DUE TO REF	LOW ATTACHMENT.	PROCESS DUE TO /	A HIGHER REFLOW TEMPER T IS THERFORE NOT BACK	RATURE,		
					HT EFFECTED BY		COMPATIBLE WITH	LEADED OR SOME SOLDEF EFERENCE FCI APPLICATI	RING		
			P F	OFILE & S	E, PLATING, SOL OLDER PASTE.	.DER REFLOW	SPECIFICATION.	LILINENCE ICI AITEICATI	- ON		
			(4) c	ONTACTS I	N ROWS A.C.F.G.	J,K,M,P,R AND T	\mathbf{O}	ETS THE EUROPEAN UNIO			
			↓ AF	E SINGLE	BEAM CONTACTS,		IN GS-22-008. PR	OTHER COUNTRY REGULATI	IES DIRECTIVE IS		
)				OTE: CONT	ISED AS GROUND F ACTS IN ROWS J	& K ARE		IE LOT CODE NUMBER MAR)N.	
				TTED	TOGETHER [COMM	IONEDJ)					
C			\sim		N ROWS B,D,F,H, AM CONTACTS,	L,N,Q AND S					
					ISED AS SIGNAL F	PINS.					
	spec ref	specref -				2010/11/01	projection	mm	size	scale	
	tolerance	TOLE	ANCES UNLESS		eng Nickor Zuo	2011/06/13				:	
D	ASME YI	SME YI4.5 OTHERWISE SPECIFI				2011/06/24 2011/06/27			ecn no	ELX-DG-003943	
			0.X	±0.30			product family	GIG-Array 2	rel level	Releas	
	surface	Linear	0.XX	± 0.00 ± 0.10		– + GIG-Array		<u>ත</u>	10030626		
		\vee	0.XXX	±0.05			SY. 200 SIG. POS.				
	_	angular	0°	$\pm 2^{\circ}$	www.fci.com	cat. no.	Pr	oduct - Custome	r Drw s	heet 5 of 5	